Ĺ	Hits	Search Text	DB	Time stamp
Number	111100			
15	4	(("6329298") or ("6099598") or	USPAT	2003/06/10
1.0	5	("4985113") or ("5670421")).PN. (("6329298") or ("6099598") or	USPAT	11:38 2003/06/10
16	) °	("4985113") or ("5670421") or	USPAI	13:56
		("6350687")).PN.		15.50
_	2		USPAT	2003/06/10
				11:25
_	581	438/687	USPAT;	2002/02/14
			EPO; JPO; DERWENT	09:10
_	0	438/687 and (anti-corrosion adj treat\$5)	USPAT;	2002/02/05
		l	EPO; JPO;	12:48
			DERWENT	
-	0	1 , , , , ,	USPAT;	2002/10/21
		adj inhibit\$5)) adj treat\$5)	EPO; JPO;	13:59
	0	   438/687 and ((corros\$5 adj inhibit\$5) adj	DERWENT USPAT;	2002/02/14
•	١	treat\$5)	EPO; JPO;	09:17
		CICACÇO	DERWENT	05.17
_	2	(((corros\$5 adj inhibit\$5) adj treat\$5))	USPAT;	2002/02/05
		and semiconductor	EPO; JPO;	12:50
		1	DERWENT	2002/02/05
_	16	(anti-corrosion adj treat\$5) and semiconductor	USPAT; EPO; JPO;	2002/02/05
		Seurconductor	DERWENT	12.30
_	18	(((anti-corrosion or (corros\$5 adj	USPAT;	2003/06/04
		inhibit\$5)) adj treat\$5)) and	EPO; JPO;	08:57
		semiconductor	DERWENT	
-	186	((corros\$5 adj inhibit\$5) adj treat\$5)	USPAT;	2002/02/05 12:56
			EPO; JPO; DERWENT	12:56
_	223	anti-corrosion adj treat\$5	USPAT;	2002/08/06
			EPO; JPO;	14:53
			DERWENT	
<b>-</b>	407	((anti-corrosion or (corros\$5 adj	USPAT;	2002/02/05
		inhibit\$5)) adj treat\$5)	EPO; JPO; DERWENT	13:12
_	3	(("6329298") or ("4668335") or	USPAT	2002/02/05
		("6323131")).PN.		13:43
_	5218	anti-corrosive	USPAT;	2002/10/21
			EPO; JPO;	13:43
	946	anti-corrosive and copper	DERWENT USPAT;	2002/02/14
_	940	anti-collosive and copper	EPO; JPO;	09:18
			DERWENT	-
_	450808	copper	USPAT;	2002/10/21
			EPO; JPO;	13:57
	946	   copper and anti-corrosive	DERWENT USPAT;	2002/02/14
	540	copper and anti-corresive	EPO; JPO;	09:28
			DERWENT	
-	0	(copper and anti-corrosive) and	USPAT;	2002/02/14
		(hetero-cyclic)	EPO; JPO;	09:19
_	2	(copper and anti-corrosive) and (hetero	DERWENT USPAT;	2002/02/14
		adj cyclic)	EPO; JPO;	09:19
			DERWENT	
-	0		USPAT;	2002/02/14
		adj cyclic)) and (indazole)	EPO; JPO;	09:29
	ا ۾	/company and anti-goni	DERWENT	2002/02/14
_	4	(copper and anti-corrosive) and (indazole)	USPAT; EPO; JPO;	09:24
		111111111111111111111111111111111111111	DERWENT	
-	О	((copper and anti-corrosive) and	USPAT;	2002/02/14
		(indazole)) and semiconductor	EPO; JPO;	09:29
	0175		DERWENT	2002/02/14
	2175	copper and ((anti-corrosive) or (anti adj corrosion))	USPAT; EPO; JPO;	2002/02/14
		COLLOSION,	DERWENT	10.20
	L			

	r	<del> </del>		10000
-	0	(	USPAT;	2002/02/14
		adj corrosion))) and (indazole)) and	EPO; JPO;	09:30
		semiconductor	DERWENT	
-	12	(copper and ((anti-corrosive) or (anti	USPAT;	2002/02/14
		adj corrosion))) and (indazole)	EPO; JPO;	10:29
		au our our on the contract of	DERWENT	1
ŀ	171	(gammam and ((anti gammagira) an (anti	USPAT;	2002/02/19
-	1 1/1	(copper and ((anti-corrosive) or (anti		
		adj corrosion))) and semiconductor	EPO; JPO;	12:34
			DERWENT	
_	0	((copper and ((anti-corrosive) or (anti	USPAT;	2002/02/14
		adj corrosion))) and semiconductor) and	EPO; JPO;	10:02
		(indazole)	DERWENT	
<u> </u>	52420	copper and ((anticorros\$3) or (corros\$3))	USPAT;	2002/02/14
_	1 32420	copper and ((anticollosys) or (corrosys))		10:29
			EPO; JPO;	10:29
		l	DERWENT	
-	163	(copper and ((anticorros\$3) or	USPAT;	2002/02/14
		(corros\$3))) and (indazole)	EPO; JPO;	10:29
			DERWENT	
_	20	((copper and ((anticorros\$3) or	USPAT;	2002/02/14
	-	(corros\$3))) and (indazole)) and	EPO; JPO;	10:32
				10.32
		semiconductor	DERWENT	/
-	16	1 ' 1 - 1	USPAT;	2002/02/14
		(corros\$3))) and (indazole)) and	EPO; JPO;	14:37
		(interconnect\$3 or wir\$4 or (sheet adj	DERWENT	
		metal))		
l _	3	, · ·	USPAT	2002/02/14
_	3		OSEAL	,
		("5455202")).PN.		14:38
-	172	(copper and ((anti-corrosive) or (anti	USPAT;	2002/02/19
		adj corrosion))) and semiconductor	EPO; JPO;	12:39
			DERWENT	
_	3	((copper and ((anti-corrosive) or (anti	USPAT;	2002/02/19
		adj corrosion))) and semiconductor) and	EPO; JPO;	12:38
				12.30
		(SiON or (silicon adj oxygen adj	DERWENT	
	•	nitrogen))		l
_	2176	(copper and ((anti-corrosive) or (anti	USPAT;	2002/02/19
		adj corrosion)))	EPO; JPO;	12:38
			DERWENT	
l _	3	(((copper and ((anti-corrosive) or (anti	USPAT;	2002/02/19
		adj corrosion)))) and (SiON or (silicon	EPO; JPO;	12:39
				12.39
		adj oxygen adj nitrogen))) and	DERWENT	
	_	semiconductor		1
-	23		USPAT;	2002/02/19
		adj corrosion))) ) and (SiON or (silicon	EPO; JPO;	12:39
		adj oxygen adj nitrogen))	DERWENT	
-	609	(438/687).CCLS.	USPAT;	2002/08/06
		,	US-PGPUB;	14:53
			EPO; JPO;	
	ĺ			]
			DERWENT;	1
	l . <u>.</u>		IBM_TDB	1 2222 /22 /23
-	484110	copper	USPAT;	2002/08/06
			US-PGPUB;	14:53
			EPO; JPO;	
[			DERWENT;	
			IBM TDB	
	026470	gappar or /"gu"\		2002/08/06
-	836479	copper or ("cu")	USPAT;	1
	[		US-PGPUB;	14:54
			EPO; JPO;	
	1		DERWENT;	
	İ		IBM TDB	
l <b>-</b>	235539	(copper or ("cu")) and treat\$5	USPAT;	2002/08/06
		, <u></u>	US-PGPUB;	14:56
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
<b> </b>	4708	((copper or ("cu")) and treat\$5) and	USPAT;	2002/08/06
		(corros\$5 adj (inhibit\$5 or treat\$5))	US-PGPUB;	14:58
			EPO; JPO;	
1	1		DERWENT;	
			IBM TDB	
	l		T T T T T D D	L

		r	,	T
-	255	(((copper or ("cu")) and treat\$5) and (corros\$5 adj (inhibit\$5 or treat\$5))) and semiconductor	USPAT; US-PGPUB; EPO; JPO;	2002/08/06 14:58
			DERWENT; IBM TDB	
-	38	<pre>((((copper or ("cu")) and treat\$5) and (corros\$5 adj (inhibit\$5 or treat\$5))) and semiconductor) and (anti-corros\$5 or (anti adj corros\$5))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/06 14:59
-	1	- · · · · · · · · · · · · · · · · · · ·	IBM_TDB USPAT	2002/08/06
_	0	   ((anti-corrosive or (anti adj corrosive))	USPAT;	15:08   2002/10/21
		adj treat\$5) same ((copper-diffus\$4 or (copper adj diffus\$4)) adj (stop\$5 or barrier) adj (layer or film))	US-PGPUB; EPO; JPO; DERWENT; IBM TDB	13:50
-	129	(anti-corrosive or (anti adj corrosive)) adj treat\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/10/21 14:55
_	7	((anti-corrosive or (anti adj corrosive)) adj treat\$5) and semiconductor	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 14:01
-	483451	copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 13:58
-	121	<pre>copper and ((anti-corrosion or (anti adj corros\$4) or (corros\$5 adj inhibit\$5)) adj treat\$5)</pre>	USPAT; EPO; JPO; DERWENT	2002/10/21 14:01
_	139	<pre>copper and ((anti-corrosion or (anti adj corros\$4) or (corros\$5 adj inhibit\$5)) adj treat\$5)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21
_	24	<pre>(copper and ((anti-corrosion or (anti adj corros\$4) or (corros\$5 adj inhibit\$5)) adj treat\$5)) and semiconductor</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 14:54
-	0	<pre>(semiconductor adj substrate) same  ((anti-corrosive or (anti adj corrosive)) adj treat\$5)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 14:56
-	1	("6350687").PN.	USPAT	2002/10/22 14:23
-	0	("jp11003892").PN.	JPO	2002/10/22   13:07
-	3	(("6350687") or ("5670421") or ("6323131")).PN.	USPAT	2002/10/22   14:24
-	57		USPAT; EPO; JPO; DERWENT	2003/06/04 09:01
-	79		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/04 10:21
-	1	(((anticorros\$5 or anti-corros\$5 or (anti adj corros\$5)) or (corros\$5 adj inhibit\$5)) adj (treat\$5)) and ((cu or copper) adj (diffus\$6 adj (barrier or stop\$6))) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/04 10:20

	1	(((anticorros\$5 or anti-corros\$5 or (anti	USPAT;	2003/06/04
		adj corros\$5)) or (corros\$5 adj	US-PGPUB;	10:20
		inhibit\$5)) adj (treat\$5)) and ((cu or	EPO; JPO;	
	İ	copper) adj (diffus\$6 adj (barrier or	DERWENT;	
		stop\$6)))	IBM TDB	
-	37	((((anticorros\$5 or anti-corros\$5 or	USPAT;	2003/06/04
		(anti adj corros\$5)) or (corros\$5 adj	US-PGPUB;	10:21
		inhibit\$5)) adj (treat\$5)) and	EPO; JPO;	
		semiconductor) and (cu or copper)	DERWENT;	
1			IBM_TDB	
-	55	((((anticorros\$5 or anti-corros\$5 or	USPAT;	2003/06/04
		(anti adj corros\$5)) or (corros\$5 adj	US-PGPUB;	10:21
		inhibit\$5)) adj (treat\$5)) and	EPO; JPO;	
	•	semiconductor) and (cu or copper)	DERWENT;	
1	1		IBM_TDB	